

IN THE CLAIMS:

Please amend the claims as follows:

1. (Twice amended) A vertical surface mount semiconductor device, comprising:
a semiconductor device having a plurality of bond pads disposed on a surface of said semiconductor device adjacent an edge thereof and arranged substantially in-line and having a plurality of conductive bumps [disposed adjacent] secured to selected bond pads, each of said conductive bumps configured to form a conductive joint between at least one of said selected bond pads and a corresponding terminal of a substrate upon positioning said semiconductor device substantially vertically relative to said substrate.

9. (Twice amended) A vertical surface mount semiconductor device, comprising:
a semiconductor device having a plurality of bond pads disposed on a surface of said semiconductor device adjacent an edge thereof and arranged substantially in-line, selected bond pads of said plurality of bond pads having conductive bumps [adjacent] secured thereto, said conductive bumps configured to form a joint between said selected bond pads and corresponding terminals of a carrier substrate upon substantially perpendicular orientation of said semiconductor device on said carrier substrate; and
a support member, at least a portion of which is disposed proximate said edge of said semiconductor device.

13. (Twice amended) A chip-on-board assembly, comprising:
a substrate with a plurality of terminals;
a semiconductor device configured to be positioned substantially perpendicularly relative to said substrate, said semiconductor device having a plurality of bond pads on a surface thereof, each of said plurality of bond pads being located adjacent an edge of said surface and arranged substantially in-line; and